

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

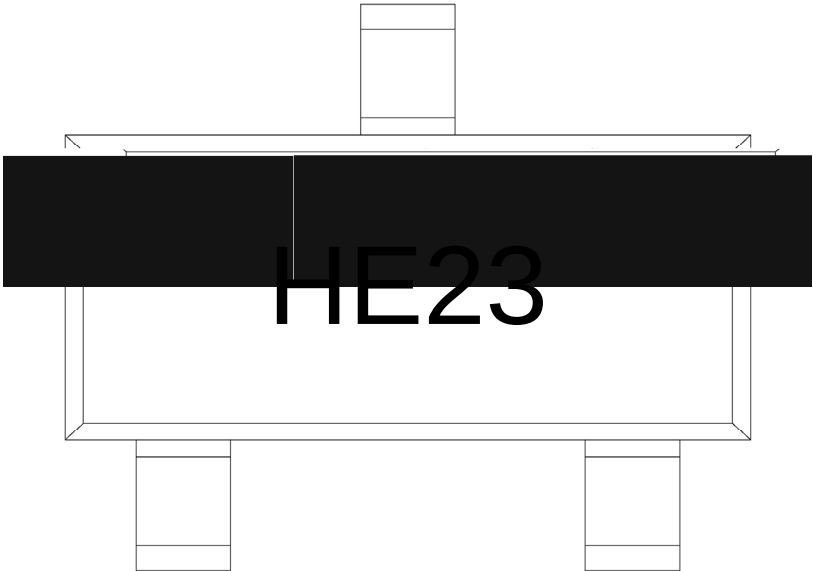
Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	50	V
Input Voltage	V_{IN}	30	V
		-5.0	V
Output Current	I_O	100	mA
Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	$V_{CC}=5.0V$ $I_O=100\text{ A}$	0.5			V
Input Voltage(ON)	$V_{I(on)}$	$V_O=0.3V$ $I_O=5.0mA$			1.3	V
Output Voltage	$V_{O(on)}$	$I_O=5.0mA$ $I_I=0.25mA$		0.1	0.3	V
Input Current	I_I	$V_I=5.0V$			1.8	mA
Output Cut-off Current	$I_{O(off)}$	$V_{CC}=50V$ $V_I=0V$			0.5	A
DC Current Gain	G_I	$V_O=5.0V$ $I_O=10mA$	80			
Transition Frequency	f_T	$V_{CE}=10V$ $I_E=-5.0mA$ $f=100MHz$		250		MHz
Resistance1	R_1		3.29	4.7	6.11	K
Resistance Ratio	R_2/R_1		8.0	10	12	

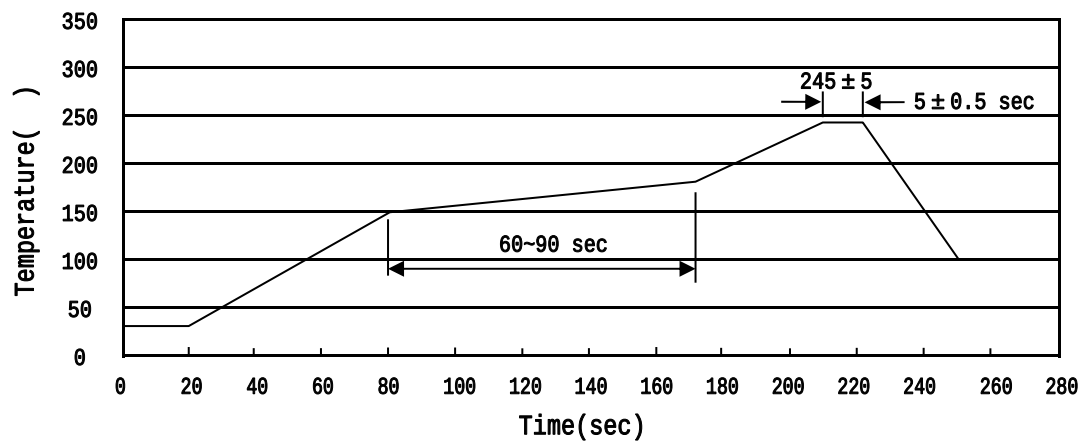


/ Marking Instructions



K	И
E23	N
Note:	
K	Company Code
E23	Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 °C , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 °C , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices